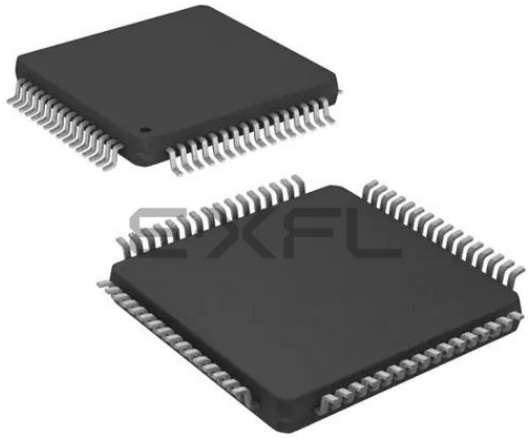

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 17x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1946-e-pt

TABLE 3-7: PIC16(L)F1946/47 MEMORY MAP, BANKS 24-31

BANK 24		BANK 25		BANK 26		BANK 27		BANK 28		BANK 29		BANK 30		BANK 31	
C00h	INDF0	C80h	INDF0	D00h	INDF0	D80h	INDF0	E00h	INDF0	E80h	INDF0	F00h	INDF0	F80h	INDF0
C01h	INDF1	C81h	INDF1	D01h	INDF1	D81h	INDF1	E01h	INDF1	E81h	INDF1	F01h	INDF1	F81h	INDF1
C02h	PCL	C82h	PCL	D02h	PCL	D82h	PCL	E02h	PCL	E82h	PCL	F02h	PCL	F82h	PCL
C03h	STATUS	C83h	STATUS	D03h	STATUS	D83h	STATUS	E03h	STATUS	E83h	STATUS	F03h	STATUS	F83h	STATUS
C04h	FSR0L	C84h	FSR0L	D04h	FSR0L	D84h	FSR0L	E04h	FSR0L	E84h	FSR0L	F04h	FSR0L	F84h	FSR0L
C05h	FSR0H	C85h	FSR0H	D05h	FSR0H	D85h	FSR0H	E05h	FSR0H	E85h	FSR0H	F05h	FSR0H	F85h	FSR0H
C06h	FSR1L	C86h	FSR1L	D06h	FSR1L	D86h	FSR1L	E06h	FSR1L	E86h	FSR1L	F06h	FSR1L	F86h	FSR1L
C07h	FSR1H	C87h	FSR1H	D07h	FSR1H	D87h	FSR1H	E07h	FSR1H	E87h	FSR1H	F07h	FSR1H	F87h	FSR1H
C08h	BSR	C88h	BSR	D08h	BSR	D88h	BSR	E08h	BSR	E88h	BSR	F08h	BSR	F88h	BSR
C09h	WREG	C89h	WREG	D09h	WREG	D89h	WREG	E09h	WREG	E89h	WREG	F09h	WREG	F89h	WREG
C0Ah	PCLATH	C8Ah	PCLATH	D0Ah	PCLATH	D8Ah	PCLATH	E0Ah	PCLATH	E8Ah	PCLATH	F0Ah	PCLATH	F8Ah	PCLATH
C0Bh	INTCON	C8Bh	INTCON	D0Bh	INTCON	D8Bh	INTCON	E0Bh	INTCON	E8Bh	INTCON	F0Bh	INTCON	F8Bh	INTCON
C0Ch	—	C8Ch	—	D0Ch	—	D8Ch	—	E0Ch	—	E8Ch	—	F0Ch	—	F8Ch	See Table 3-9
C0Dh	—	C8Dh	—	D0Dh	—	D8Dh	—	E0Dh	—	E8Dh	—	F0Dh	—	F8Dh	
C0Eh	—	C8Eh	—	D0Eh	—	D8Eh	—	E0Eh	—	E8Eh	—	F0Eh	—	F8Eh	
C0Fh	—	C8Fh	—	D0Fh	—	D8Fh	—	E0Fh	—	E8Fh	—	F0Fh	—	F8Fh	
C10h	—	C90h	—	D10h	—	D90h	—	E10h	—	E90h	—	F10h	—	F90h	
C11h	—	C91h	—	D11h	—	D91h	—	E11h	—	E91h	—	F11h	—	F91h	
C12h	—	C92h	—	D12h	—	D92h	—	E12h	—	E92h	—	F12h	—	F92h	
C13h	—	C93h	—	D13h	—	D93h	—	E13h	—	E93h	—	F13h	—	F93h	
C14h	—	C94h	—	D14h	—	D94h	—	E14h	—	E94h	—	F14h	—	F94h	
C15h	—	C95h	—	D15h	—	D95h	—	E15h	—	E95h	—	F15h	—	F95h	
C16h	—	C96h	—	D16h	—	D96h	—	E16h	—	E96h	—	F16h	—	F96h	
C17h	—	C97h	—	D17h	—	D97h	—	E17h	—	E97h	—	F17h	—	F97h	
C18h	—	C98h	—	D18h	—	D98h	—	E18h	—	E98h	—	F18h	—	F98h	
C19h	—	C99h	—	D19h	—	D99h	—	E19h	—	E99h	—	F19h	—	F99h	
C1Ah	—	C9Ah	—	D1Ah	—	D9Ah	—	E1Ah	—	E9Ah	—	F1Ah	—	F9Ah	
C1Bh	—	C9Bh	—	D1Bh	—	D9Bh	—	E1Bh	—	E9Bh	—	F1Bh	—	F9Bh	
C1Ch	—	C9Ch	—	D1Ch	—	D9Ch	—	E1Ch	—	E9Ch	—	F1Ch	—	F9Ch	
C1Dh	—	C9Dh	—	D1Dh	—	D9Dh	—	E1Dh	—	E9Dh	—	F1Dh	—	F9Dh	
C1Eh	—	C9Eh	—	D1Eh	—	D9Eh	—	E1Eh	—	E9Eh	—	F1Eh	—	F9Eh	
C1Fh	—	C9Fh	—	D1Fh	—	D9Fh	—	E1Fh	—	E9Fh	—	F1Fh	—	F9Fh	
C20h C6Fh	Unimplemented Read as '0'	CA0h CEFh	Unimplemented Read as '0'	D20h D6Fh	Unimplemented Read as '0'	DA0h DEFh	Unimplemented Read as '0'	E20h E6Fh	Unimplemented Read as '0'	EA0h EEFh	Unimplemented Read as '0'	F20h F6Fh	Unimplemented Read as '0'	FA0h FEFh	
C70h CFFh	Accesses 70h – 7Fh	CF0h CFFh	Accesses 70h – 7Fh	D70h D7Fh	Accesses 70h – 7Fh	DF0h DFFh	Accesses 70h – 7Fh	E70h E7Fh	Accesses 70h – 7Fh	EF0h EFFh	Accesses 70h – 7Fh	F70h F7Fh	Accesses 70h – 7Fh	FF0h FFFh	Accesses 70h – 7Fh

Legend: = Unimplemented data memory locations, read as '0'.

4.0 DEVICE CONFIGURATION

Device Configuration consists of Configuration Words, Code Protection and Device ID.

4.1 Configuration Words

There are several Configuration Word bits that allow different oscillator and memory protection options. These are implemented as Configuration Word 1 at 8007h and Configuration Word 2 at 8008h.

Note:	The $\overline{\text{DEBUG}}$ bit in Configuration Word 2 is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.

4.2 Register Definitions: Configuration Words

REGISTER 4-1: CONFIG1: CONFIGURATION WORD 1

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
FCMEN	IESO	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		$\overline{\text{CPD}}$
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor is enabled
0 = Fail-Safe Clock Monitor is disabled

bit 12 **IESO:** Internal External Switchover bit
1 = Internal/External Switchover mode is enabled
0 = Internal/External Switchover mode is disabled

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
If FOSC configuration bits are set to LP, XT, HS modes:
This bit is ignored, CLKOUT function is disabled. Oscillator function on the CLKOUT pin.
All other FOSC modes:
1 = CLKOUT function is disabled. I/O function on the CLKOUT pin.
0 = CLKOUT function is enabled on the CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits(1)
11 = BOR enabled
10 = BOR enabled during operation and disabled in Sleep
01 = BOR controlled by SBOREN bit of the BORCON register
00 = BOR disabled

bit 8 **$\overline{\text{CPD}}$:** Data Code Protection bit(2)
1 = Data memory code protection is disabled
0 = Data memory code protection is enabled

bit 7 **$\overline{\text{CP}}$:** Code Protection bit(3)
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/V_{PP} Pin Function Select bit
If LVP bit = 1:
This bit is ignored.
If LVP bit = 0:
1 = $\overline{\text{MCLR}}$/V_{PP} pin function is $\overline{\text{MCLR}}$; Weak pull-up enabled.
0 = $\overline{\text{MCLR}}$/V_{PP} pin function is digital input; $\overline{\text{MCLR}}$ internally disabled; Weak pull-up under control of WPUG5 bit.

Note 1: Enabling Brown-out Reset does not automatically enable Power-up Timer.
2: The entire data EEPROM will be erased when the code protection is turned off during an erase.
3: The entire program memory will be erased when the code protection is turned off.

REGISTER 4-1: CONFIG1: CONFIGURATION WORD 1 (CONTINUED)

bit 5 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit(1)
1 = PWRT disabled
0 = PWRT enabled

bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bit
11 = WDT enabled
10 = WDT enabled while running and disabled in Sleep
01 = WDT controlled by the SWDTEN bit in the WDTCON register
00 = WDT disabled

bit 2-0 **FOSC<2:0>:** Oscillator Selection bits
111 = ECH: External Clock, High-Power mode (4-20 MHz): device clock supplied to CLKIN pin
110 = ECM: External Clock, Medium-Power mode (0.5-4 MHz): device clock supplied to CLKIN pin
101 = ECL: External Clock, Low-Power mode (0-0.5 MHz): device clock supplied to CLKIN pin
100 = INTOSC oscillator: I/O function on CLKIN pin
011 = EXTRC oscillator: External RC circuit connected to CLKIN pin
010 = HS oscillator: High-speed crystal/resonator connected between OSC1 and OSC2 pins
001 = XT oscillator: Crystal/resonator connected between OSC1 and OSC2 pins
000 = LP oscillator: Low-power crystal connected between OSC1 and OSC2 pins

Note 1: Enabling Brown-out Reset does not automatically enable Power-up Timer.
2: The entire data EEPROM will be erased when the code protection is turned off during an erase.
3: The entire program memory will be erased when the code protection is turned off.

5.2.2.3 Internal Oscillator Frequency Adjustment

The 500 kHz internal oscillator is factory calibrated. This internal oscillator can be adjusted in software by writing to the OSCTUNE register (Register 5-3). Since the HFINTOSC and MFINTOSC clock sources are derived from the 500 kHz internal oscillator a change in the OSCTUNE register value will apply to both.

The default value of the OSCTUNE register is '0'. The value is a 6-bit two's complement number. A value of 1Fh will provide an adjustment to the maximum frequency. A value of 20h will provide an adjustment to the minimum frequency.

When the OSCTUNE register is modified, the oscillator frequency will begin shifting to the new frequency. Code execution continues during this shift. There is no indication that the shift has occurred.

OSCTUNE does not affect the LFINTOSC frequency. Operation of features that depend on the LFINTOSC clock source frequency, such as the Power-up Timer (PWRT), Watchdog Timer (WDT), Fail-Safe Clock Monitor (FSCM) and peripherals, are *not* affected by the change in frequency.

5.2.2.4 LFINTOSC

The Low-Frequency Internal Oscillator (LFINTOSC) is an uncalibrated 31 kHz internal clock source.

The output of the LFINTOSC connects to a multiplexer (see Figure 5-1). Select 31 kHz, via software, using the IRCF<3:0> bits of the OSCCON register. See **Section 5.2.2.7 "Internal Oscillator Clock Switch Timing"** for more information. The LFINTOSC is also the frequency for the Power-up Timer (PWRT), Watchdog Timer (WDT) and Fail-Safe Clock Monitor (FSCM).

The LFINTOSC is enabled by selecting 31 kHz (IRCF<3:0> bits of the OSCCON register = 000) as the system clock source (SCS bits of the OSCCON register = 1x), or when any of the following are enabled:

- Configure the IRCF<3:0> bits of the OSCCON register for the desired LF frequency, and
- FOSC<2:0> = 100, or
- Set the System Clock Source (SCS) bits of the OSCCON register to '1x'

Peripherals that use the LFINTOSC are:

- Power-up Timer (PWRT)
- Watchdog Timer (WDT)
- Fail-Safe Clock Monitor (FSCM)

The Low Frequency Internal Oscillator Ready bit (LFIOFR) of the OSCSTAT register indicates when the LFINTOSC is running.

5.2.2.5 Internal Oscillator Frequency Selection

The system clock speed can be selected via software using the Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register.

The output of the 16 MHz HFINTOSC and 31 kHz LFINTOSC connects to a postscaler and multiplexer (see Figure 5-1). The Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register select the frequency output of the internal oscillators. One of the following frequencies can be selected via software:

- HFINTOSC
  - 32 MHz (requires 4x PLL)
  - 16 MHz
  - 8 MHz
  - 4 MHz
  - 2 MHz
  - 1 MHz
  - 500 kHz (default after Reset)
  - 250 kHz
  - 125 kHz
  - 62.5 kHz
  - 31.25 kHz
- LFINTOSC
  - 31 kHz

Note:	Following any Reset, the IRCF<3:0> bits of the OSCCON register are set to '0111' and the frequency selection is set to 500 kHz. The user can modify the IRCF bits to select a different frequency.

The IRCF<3:0> bits of the OSCCON register allow duplicate selections for some frequencies. These duplicate choices can offer system design trade-offs. Lower power consumption can be obtained when changing oscillator sources for a given frequency. Faster transition times can be obtained between frequency changes that use the same oscillator source.

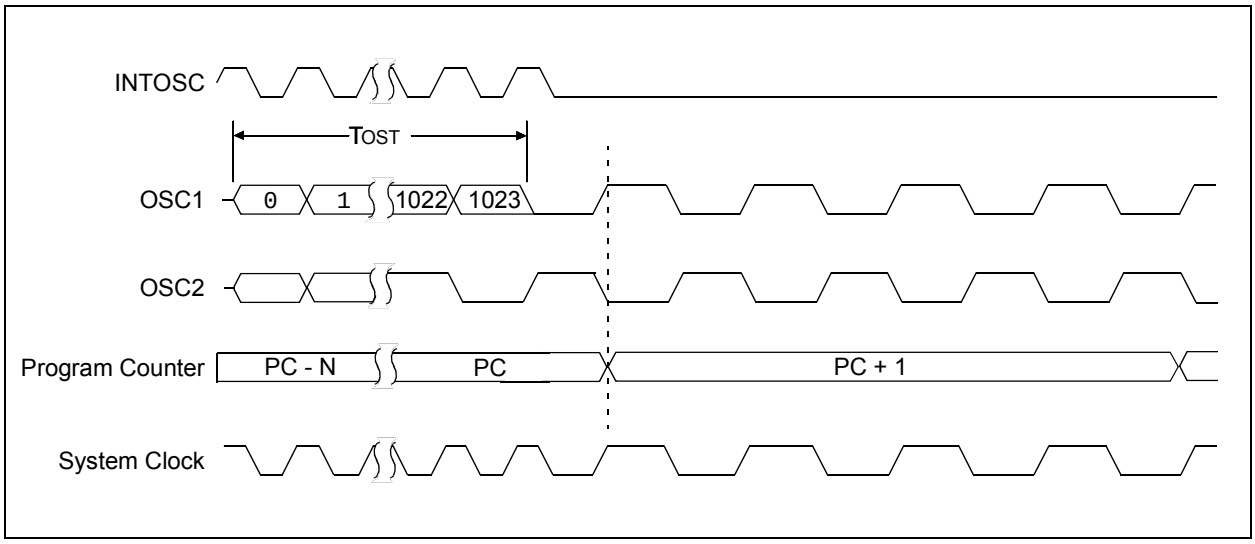
5.4.2 TWO-SPEED START-UP SEQUENCE

1. Wake-up from Power-on Reset or Sleep.
2. Instructions begin execution by the internal oscillator at the frequency set in the IRCF<3:0> bits of the OSCCON register.
3. OST enabled to count 1024 clock cycles.
4. OST timed out, wait for falling edge of the internal oscillator.
5. OSTS is set.
6. System clock held low until the next falling edge of new clock (LP, XT or HS mode).
7. System clock is switched to external clock source.

5.4.3 CHECKING TWO-SPEED CLOCK STATUS

Checking the state of the OSTS bit of the OSCSTAT register will confirm if the microcontroller is running from the external clock source, as defined by the FOSC<2:0> bits in the Configuration Words, or the internal oscillator.

FIGURE 5-8: TWO-SPEED START-UP



7.6 Register Definitions: Interrupt Control

REGISTER 7-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R-0/0
GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all active interrupts
0 = Disables all interrupts

bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all active peripheral interrupts
0 = Disables all peripheral interrupts

bit 5 **TMR0IE:** Timer0 Overflow Interrupt Enable bit
1 = Enables the Timer0 interrupt
0 = Disables the Timer0 interrupt

bit 4 **INTE:** INT External Interrupt Enable bit
1 = Enables the INT external interrupt
0 = Disables the INT external interrupt

bit 3 **IOCIE:** Interrupt-on-Change Enable bit
1 = Enables the interrupt-on-change
0 = Disables the interrupt-on-change

bit 2 **TMR0IF:** Timer0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed
0 = TMR0 register did not overflow

bit 1 **INTF:** INT External Interrupt Flag bit
1 = The INT external interrupt occurred
0 = The INT external interrupt did not occur

bit 0 **IOCIF:** Interrupt-on-Change Interrupt Flag bit
1 = When at least one of the interrupt-on-change pins changed state
0 = None of the interrupt-on-change pins have changed state

Note 1: The IOCIF Flag bit is read-only and cleared when all the interrupt-on-change flags in the IOCBF register have been cleared by software.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

12.15 PORTG Registers

PORTG is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISG (Register 12-25). Setting a TRISG bit (= 1) will make the corresponding PORTG pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISG bit (= 0) will make the corresponding PORTG pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). The exception is RG5, which is input only and its TRIS bit will always read as '1'. Example 12-1 shows how to initialize an I/O port.

Reading the PORTG register (Register 12-24) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATG). RG5 reads '0' when MCLRE = 1.

The TRISG register (Register 12-25) controls the PORTG pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISG register are maintained set when using them as analog inputs. I/O pins configured as analog inputs always read '0'.

12.15.1 ANSELG REGISTER

The ANSELG register (Register 12-27) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELG bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELG bits has no effect on digital output functions. A pin with TRIS clear and ANSEL set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

Note:	The ANSELG register must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'.

12.15.2 PORTG FUNCTIONS AND OUTPUT PRIORITIES

Each PORTG pin is multiplexed with other functions. The pins, their combined functions and their output priorities are shown in Table 12-16.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the highest priority.

Analog input and some digital input functions are not included in the list below. These input functions can remain active when the pin is configured as an output. Certain digital input functions override other port functions and are included in the priority list.

TABLE 12-16: PORTG OUTPUT PRIORITY

Pin Name	Function Priority(1)
RG0	CCP3 (CCP) P3A (CCP) SEG42 (LCD) RG0
RG1	TX2 (EUSART) CK2 (EUSART) C3OUT (Comparator) SEG43 (LCD) RG1
RG2	DT2 SEG44 (LCD) RG2
RG3	CCP4 (CCP) P3D (CCP) SEG45 (LCD) RG3
RG4	CCP5 (CCP) P1D (CCP) SEG26 (LCD) RG4
RG5	Input-only pin

Note 1: Priority listed from highest to lowest.

17.0 DIGITAL-TO-ANALOG CONVERTER (DAC) MODULE

The Digital-to-Analog Converter supplies a variable voltage reference, ratiometric with the input source, with 32 selectable output levels.

The input of the DAC can be connected to:

- External VREF pins
- VDD supply voltage
- FVR (Fixed Voltage Reference)

The output of the DAC can be configured to supply a reference voltage to the following:

- Comparator positive input
- ADC input channel
- DACOUT pin
- Capacitive Sensing module (CPS)

The Digital-to-Analog Converter (DAC) can be enabled by setting the DACEN bit of the DACCON0 register.

17.1 Output Voltage Selection

The DAC has 32 voltage level ranges. The 32 levels are set with the DACR<4:0> bits of the DACCON1 register.

The DAC output voltage is determined by the following equations:

EQUATION 17-1: DAC OUTPUT VOLTAGE

IF DACEN = 1

$$V_{OUT} = \left((V_{SOURCE+} - V_{SOURCE-}) \times \frac{DACR[4:0]}{2^5} \right) + V_{SOURCE-}$$

IF DACEN = 0 & DACLPS = 1 & DACR[4:0] = 11111

$$V_{OUT} = V_{SOURCE+}$$

IF DACEN = 0 & DACLPS = 0 & DACR[4:0] = 00000

$$V_{OUT} = V_{SOURCE-}$$

$V_{SOURCE+} = V_{DD}$, V_{REF}, *or FVR BUFFER 2*

$V_{SOURCE-} = V_{SS}$

17.2 Ratiometric Output Level

The DAC output value is derived using a resistor ladder with each end of the ladder tied to a positive and negative voltage reference input source. If the voltage of either input source fluctuates, a similar fluctuation will result in the DAC output value.

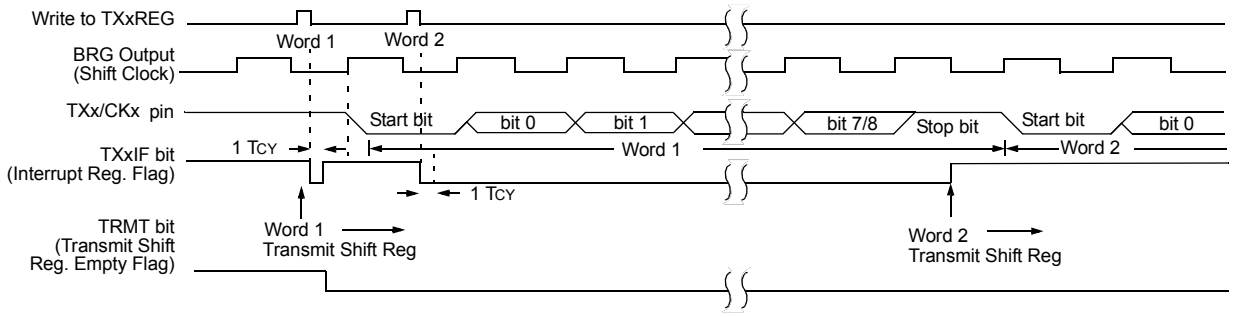
The value of the individual resistors within the ladder can be found in **Section 30.0 "Electrical Specifications"**.

17.3 DAC Voltage Reference Output

The DAC can be output to the DACOUT pin by setting the DACOE bit of the DACCON0 register to '1'. Selecting the DAC reference voltage for output on the DACOUT pin automatically overrides the digital output buffer and digital input threshold detector functions of that pin. Reading the DACOUT pin when it has been configured for DAC reference voltage output will always return a '0'.

Due to the limited current drive capability, a buffer must be used on the DAC voltage reference output for external connections to DACOUT. Figure 17-2 shows an example buffering technique.

FIGURE 25-4: ASYNCHRONOUS TRANSMISSION (BACK-TO-BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 25-1: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	299
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	299
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	90
PIE1	—	ADIE	RC1IE	TX1IE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	91
PIE4	—	—	RC2IE	TX2IE	—	—	BCL2IE	SSP2IE	94
PIR1	—	ADIF	RC1IF	TX1IF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	95
PIR4	—	—	RC2IF	TX2IF	—	—	BCL2IF	SSP2IF	98
RC1STA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	298
RC2STA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	298
SP1BRGL	EUSART1 Baud Rate Generator, Low Byte								300*
SP1BRGH	EUSART1 Baud Rate Generator, High Byte								300*
SP2BRGL	EUSART2 Baud Rate Generator, Low Byte								300*
SP2BRGH	EUSART2 Baud Rate Generator, High Byte								300*
TX1REG	EUSART1 Transmit Register								292*
TX1STA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	297
TX2REG	EUSART2 Transmit Register								292*
TX2STA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	297

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for asynchronous transmission.

* Page provides register information.

REGISTER 27-3: LCDREF: LCD REFERENCE VOLTAGE CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	U-0
LCDIRE	LCDIRS	LCDIRI	—	VLCD3PE	VLCD2PE	VLCD1PE	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	C = Only clearable bit

bit 7 **LCDIRE:** LCD Internal Reference Enable bit
1 = Internal LCD Reference is enabled and connected to the Internal Contrast Control circuit
0 = Internal LCD Reference is disabled

bit 6 **LCDIRS:** LCD Internal Reference Source bit
If LCDIRE = 1:
0 = Internal LCD Contrast Control is powered by V_{DD}
1 = Internal LCD Contrast Control is powered by a 3.072V output of the FVR.
If LCDIRE = 0:
Internal LCD Contrast Control is unconnected. LCD bandgap buffer is disabled.

bit 5 **LCDIRI:** LCD Internal Reference Ladder Idle Enable bit
Allows the Internal FVR buffer to shut down when the LCD Reference Ladder is in power mode 'B'
1 = When the LCD Reference Ladder is in power mode 'B', the LCD Internal FVR buffer is disabled.
0 = The LCD Internal FVR Buffer ignores the LCD Reference Ladder Power mode.

bit 4 **Unimplemented:** Read as '0'

bit 3 **VLCD3PE:** VLCD3 Pin Enable bit
1 = The VLCD3 pin is connected to the internal bias voltage LCDBIAS3**(1)**
0 = The VLCD3 pin is not connected

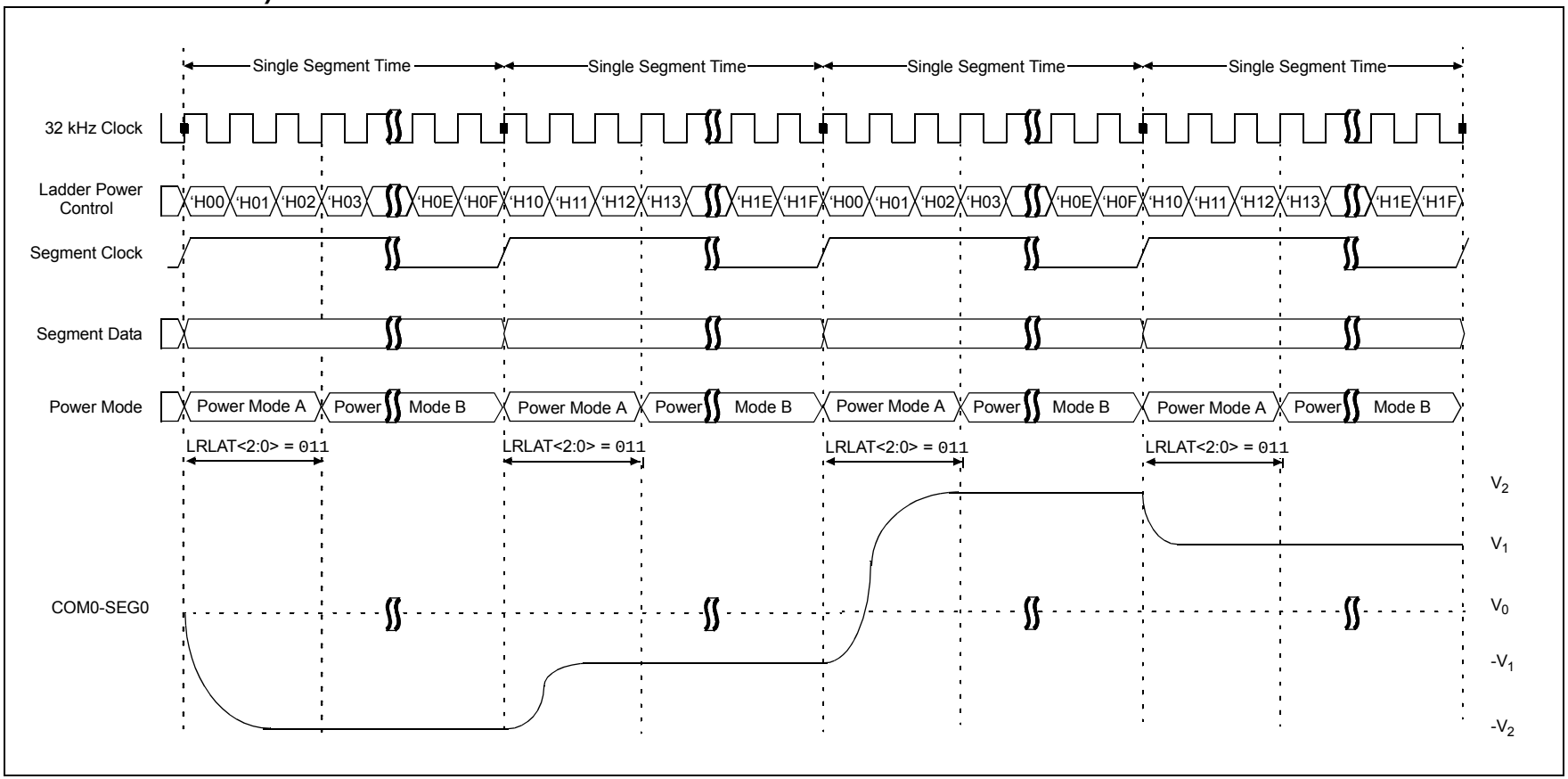
bit 2 **VLCD2PE:** VLCD2 Pin Enable bit
1 = The VLCD2 pin is connected to the internal bias voltage LCDBIAS2**(1)**
0 = The VLCD2 pin is not connected

bit 1 **VLCD1PE:** VLCD1 Pin Enable bit
1 = The VLCD1 pin is connected to the internal bias voltage LCDBIAS1**(1)**
0 = The VLCD1 pin is not connected

bit 0 **Unimplemented:** Read as '0'

Note 1: Normal pin controls of TRISx and ANSELx are unaffected.

FIGURE 27-6: LCD INTERNAL REFERENCE LADDER POWER MODE SWITCHING DIAGRAM – TYPE B WAVEFORM (1/2 MUX, 1/2 BIAS DRIVE)



30.5 DC Characteristics: PIC16(L)F1946/47-I/E

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O PORT:					
D032		with TTL buffer	—	—	0.8	V	4.5V ≤ VDD ≤ 5.5V
D032A			—	—	0.15 VDD	V	1.8V ≤ VDD ≤ 4.5V
D033		with Schmitt Trigger buffer	—	—	0.2 VDD	V	2.0V ≤ VDD ≤ 5.5V
		with I^2C levels	—	—	0.3 VDD	V	
		with SMBus levels	—	—	0.8	V	2.7V ≤ VDD ≤ 5.5V
D034		$\overline{MCLR}$, OSC1 (RC mode)(1)	—	—	0.2 VDD	V	
D034A		OSC1 (HS mode)	—	—	0.3 VDD	V	
	VIH	**Input High Voltage**					
		I/O ports:					
D040		with TTL buffer	2.0	—	—	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25 VDD + 0.8	—	—	V	1.8V ≤ VDD ≤ 4.5V
D041		with Schmitt Trigger buffer	0.8 VDD	—	—	V	2.0V ≤ VDD ≤ 5.5V
		with I^2C levels	0.7 VDD	—	—	V	
		with SMBus levels	2.1	—	—	V	2.7V ≤ VDD ≤ 5.5V
D042		$\overline{MCLR}$	0.8 VDD	—	—	V	
D043A		OSC1 (HS mode)	0.7 VDD	—	—	V	
D043B		OSC1 (RC mode)	0.9 VDD	—	—	V	**(Note 1)** VDD > 2.0V
	IIL	**Input Leakage Current(2)**					
D060		I/O ports	—	± 5	± 125	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance @ 85°C
				± 5	± 1000	nA	125°C
D061		$\overline{MCLR}$(3)	—	± 50	± 200	nA	VSS ≤ VPIN ≤ VDD @ 85°C
	IPUR	**Weak Pull-up Current**					
D070*			25 25	100 140	200 300	μA	VDD = 3.3V, VPIN = VSS VDD = 5.0V, VPIN = VSS
	VOL	**Output Low Voltage(4)**					
D080		I/O ports	—	—	0.6	V	IOL = 8mA, VDD = 5V IOL = 6mA, VDD = 3.3V IOL = 1.8mA, VDD = 1.8V
	VOH	**Output High Voltage(4)**					
D090		I/O ports	VDD - 0.7	—	—	V	IOH = 3.5mA, VDD = 5V IOH = 3mA, VDD = 3.3V IOH = 1mA, VDD = 1.8V
		Capacitive Loading Specs on Output Pins					
D101*	COSC2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101A*	CIO	All I/O pins	—	—	50	pF	
		VCAP Capacitor Charging					
D102		Charging current	—	200	—	μA	
D102A		Source/sink capability when charging complete	—	0.0	—	mA	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

2: Negative current is defined as current sourced by the pin.

3: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

4: Including OSC2 in CLKOUT mode.

TABLE 30-1: CLOCK OSCILLATOR TIMING REQUIREMENTS (CONTINUED)

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS05*	TosR, TosF	External CLKIN Rise, External CLKIN Fall	0 0 0	— — —	∞ ∞ ∞	ns ns ns	LP oscillator XT oscillator HS oscillator

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

TABLE 30-2: OSCILLATOR PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristic**	**Freq. Tolerance**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS08	HFOSC	Internal-Calibrated HFINTOSC Frequency(1)	±2%	—	16.0	—	MHz	0°C ≤ TA ≤ +60°C, VDD ≥ 2.5V
			±3%	—	16.0	—	MHz	60°C ≤ TA ≤ +85°C, VDD ≥ 2.5V
			±5%	—	16.0	—	MHz	-40°C ≤ TA ≤ +125°C
OS08A	MFOSC	Internal-Calibrated MFINTOSC Frequency(1)	±2%	—	500	—	kHz	0°C ≤ TA ≤ +60°C, VDD ≥ 2.5V
			±3%	—	500	—	kHz	60°C ≤ TA ≤ +85°C, VDD ≥ 2.5V
			±5%	—	500	—	kHz	-40°C ≤ TA ≤ +125°C
OS09	LFOSC	Internal LFINTOSC Frequency	—	—	31	—	kHz	-40°C ≤ TA ≤ +125°C
OS10*	TIOSC ST	HFINTOSC Wake-up from Sleep Start-up Time MFINTOSC Wake-up from Sleep Start-up Time	— —	— —	3.2 24	8 35	µs µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

TABLE 30-3: PLL CLOCK TIMING SPECIFICATIONS (VDD = 2.7V TO 5.5V)

Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
F10	FOSC	Oscillator Frequency Range	4	—	8	MHz	
F11	FSYS	On-Chip VCO System Frequency	16	—	32	MHz	
F12	TRC	PLL Start-up Time (Lock Time)	—	—	2	ms	
F13*	ΔCLK	CLKOUT Stability (Jitter)	-0.25%	—	+0.25%	%	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 30-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
30	TMCL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	
31	TWDTLP	Watchdog Timer Time-out Period	10	16	27	ms	VDD = 3.3V-5V, 1:512 Prescaler used
32	TOST	Oscillator Start-up Timer Period(1)	—	1024	—	TOSC	
33*	TPWRT	Power-up Timer Period, $\overline{\text{PWRTE}}$ = 0	40	65	140	ms	
34*	TIOZ	I/O high-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	2.0	μs	
35	VBOR	Brown-out Reset Voltage(2)	2.55 1.80	2.70 1.90	2.85 2.11	V V	BORV = 0 BORV = 1
36*	VHYST	Brown-out Reset Hysteresis	0	25	50	mV	-40°C to +85°C
37*	TBORDC	Brown-out Reset DC Response Time	1	3	35	μs	VDD ≤ VBOR

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: By design, the Oscillator Start-up Timer (OST) counts the first 1024 cycles, independent of frequency.

2: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 μF and 0.01 μF values in parallel are recommended.

FIGURE 30-10: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

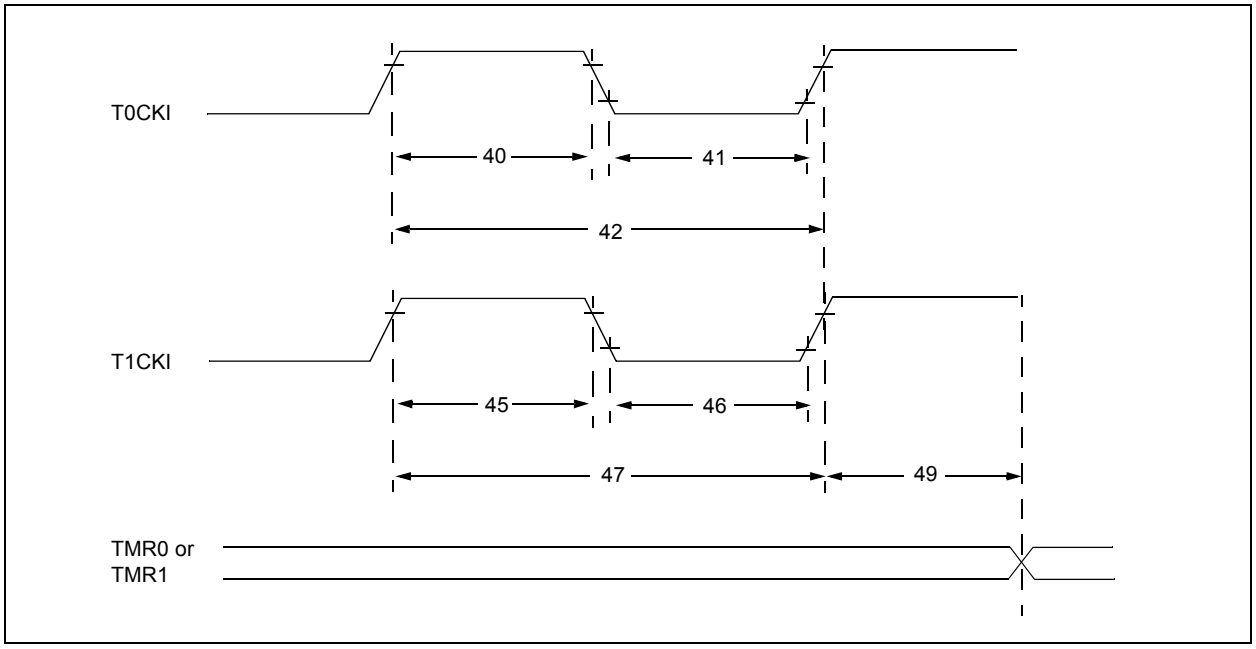


TABLE 30-9: PIC16(L)F1946/47 A/D CONVERSION REQUIREMENTS

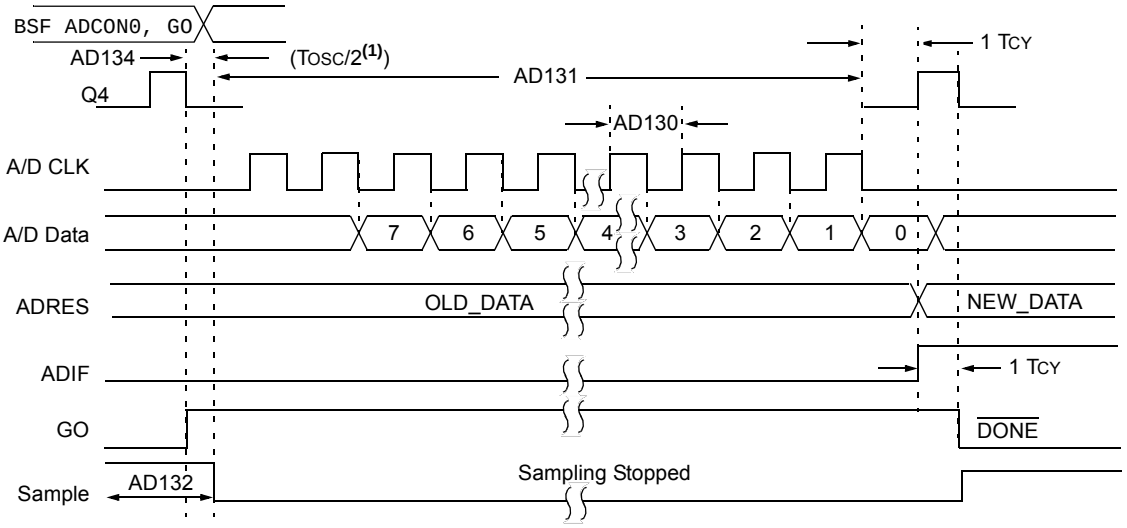
Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD130*	TAD	A/D Clock Period	1.0	—	9.0	µs	TOSC-based
		A/D Internal RC Oscillator Period	1.0	2.5	6.0	µs	ADCS<1:0> = 11 (ADRC mode)
AD131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	11	—	TAD	Set GO/$\overline{\text{DONE}}$ bit to conversion complete
AD132*	TACQ	Acquisition Time	—	5.0	—	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The ADRES register may be read on the following TCY cycle.

FIGURE 30-12: PIC16(L)F1946/47 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 31-19: IDD, LFINTOSC MODE, FOSC = 32 kHz, PIC16LF1946/47 ONLY

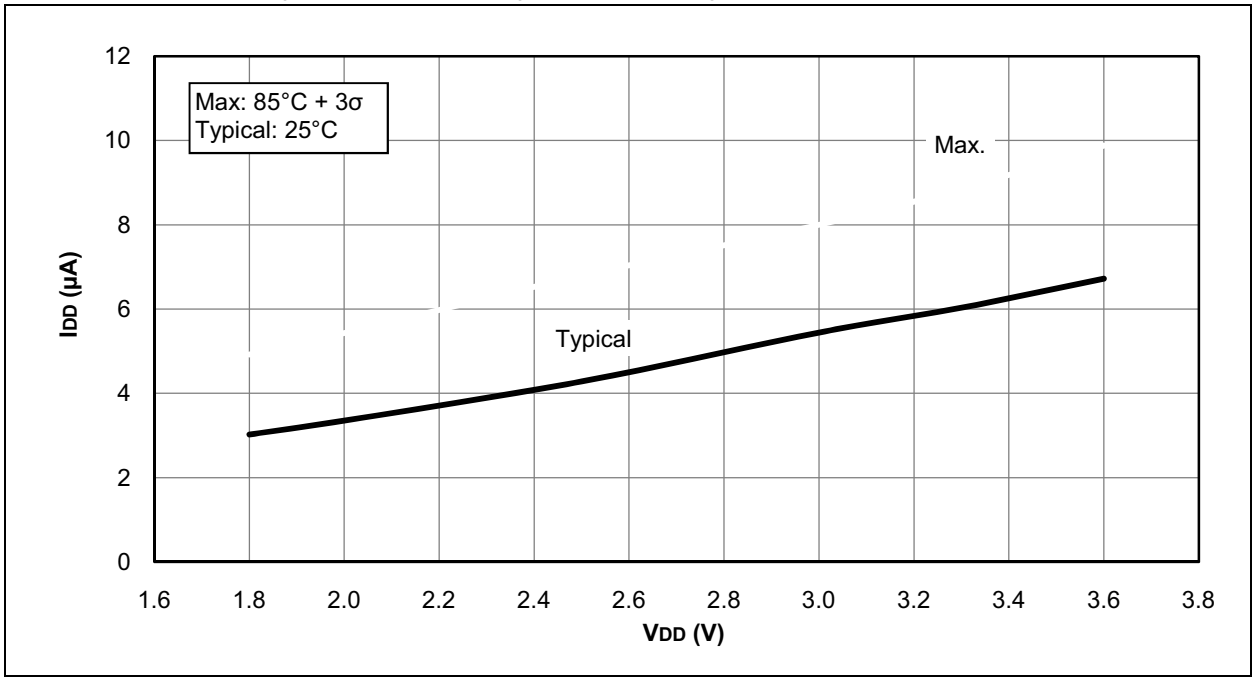


FIGURE 31-20: IDD, LFINTOSC MODE, FOSC = 32 kHz, PIC16F1946/47 ONLY

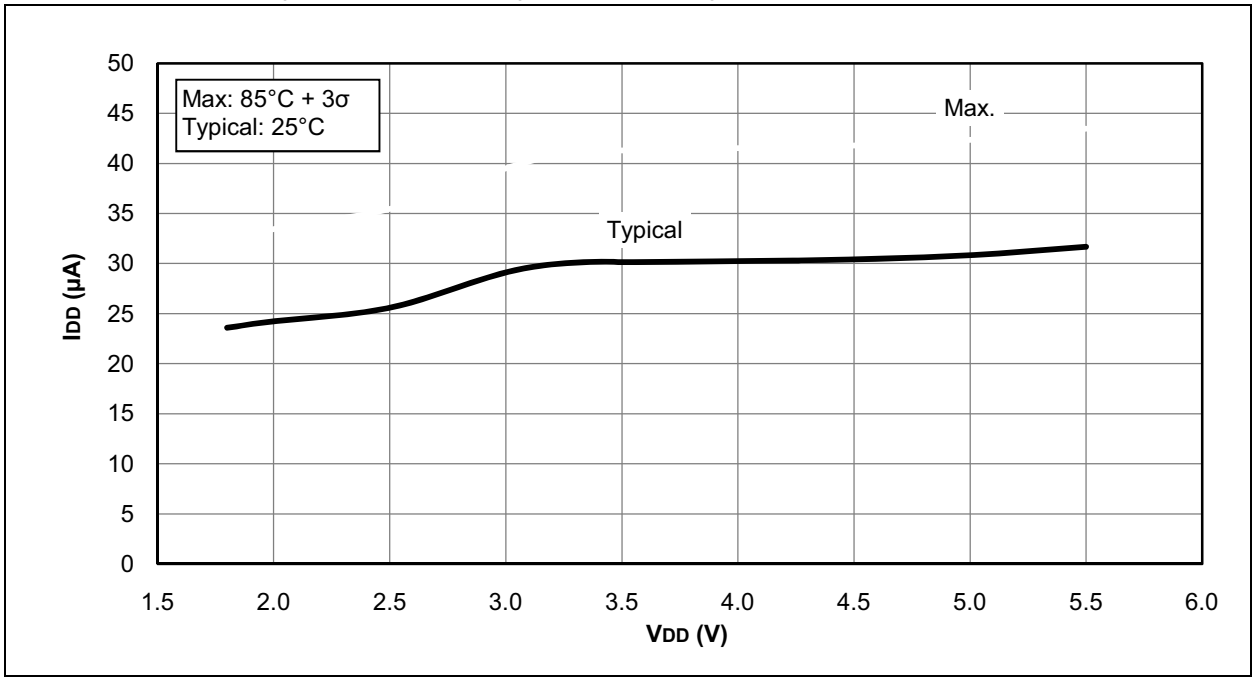


FIGURE 31-39: IPD, TIMER1 OSCILLATOR, FOSC = 32 kHz, PIC16LF1946/47 ONLY

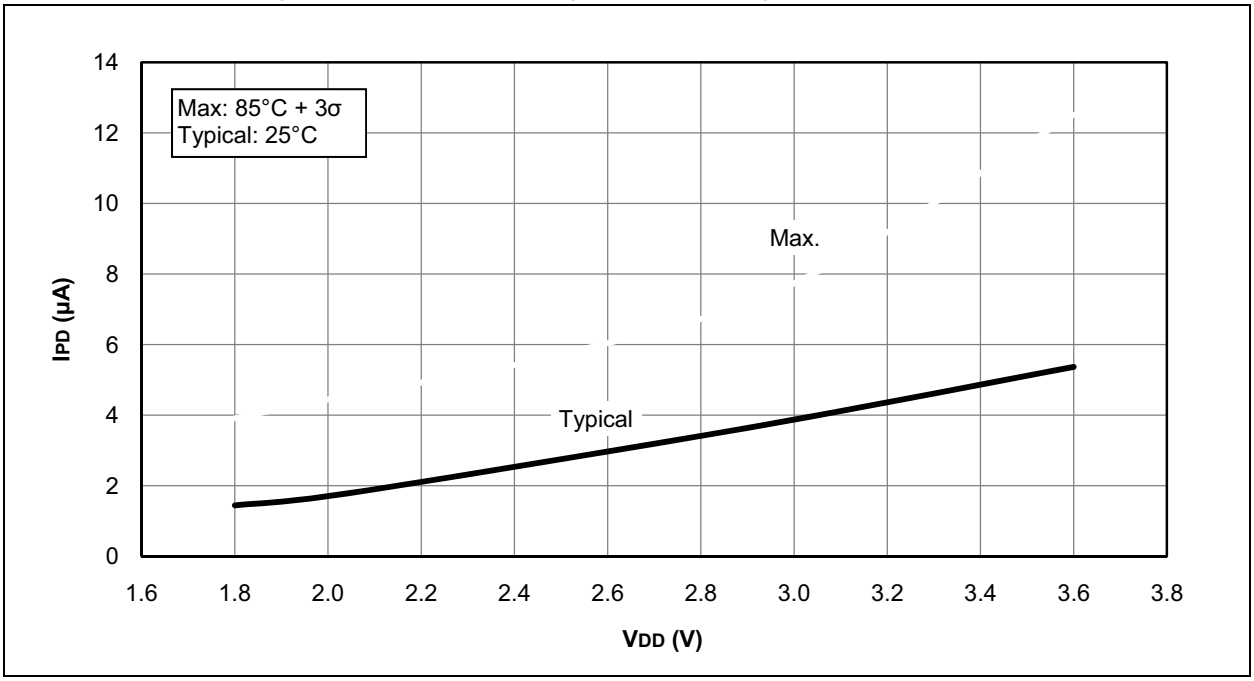


FIGURE 31-40: IPD, TIMER1 OSCILLATOR, FOSC = 32 kHz, PIC16F1946/47 ONLY

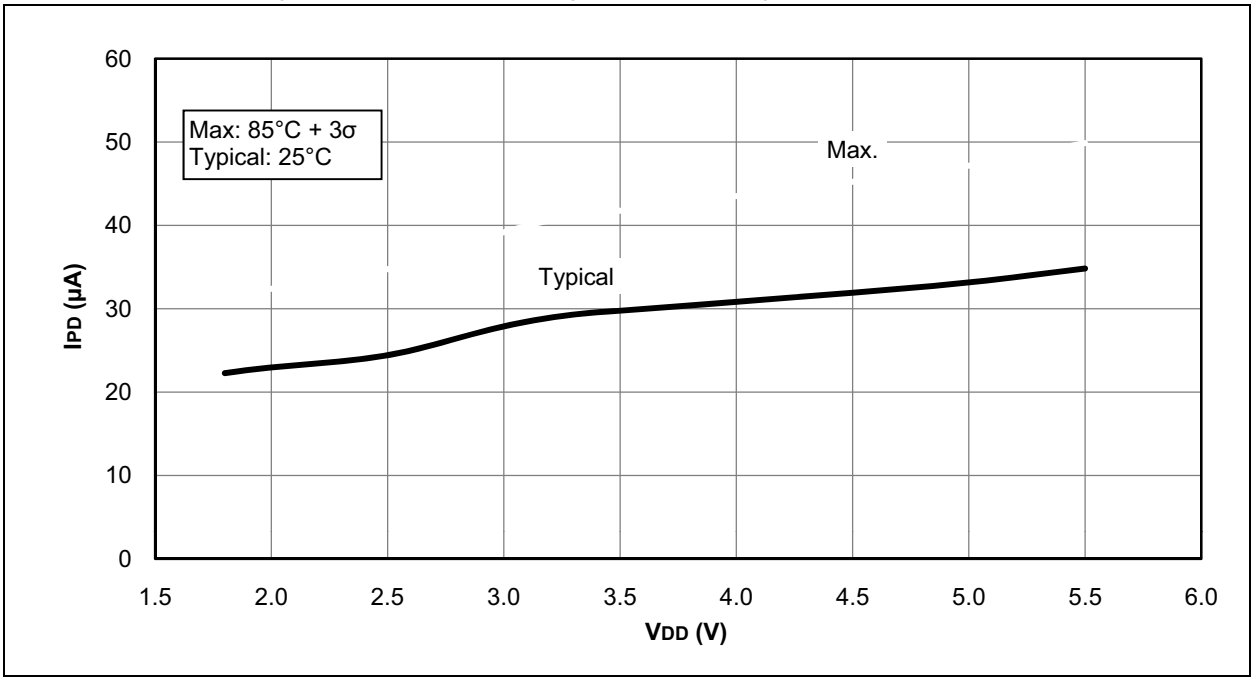


FIGURE 31-43: IPD, CAPACITIVE SENSING (CPS) MODULE, MEDIUM-CURRENT RANGE, CPSRM = 0, PIC16LF1946/47 ONLY

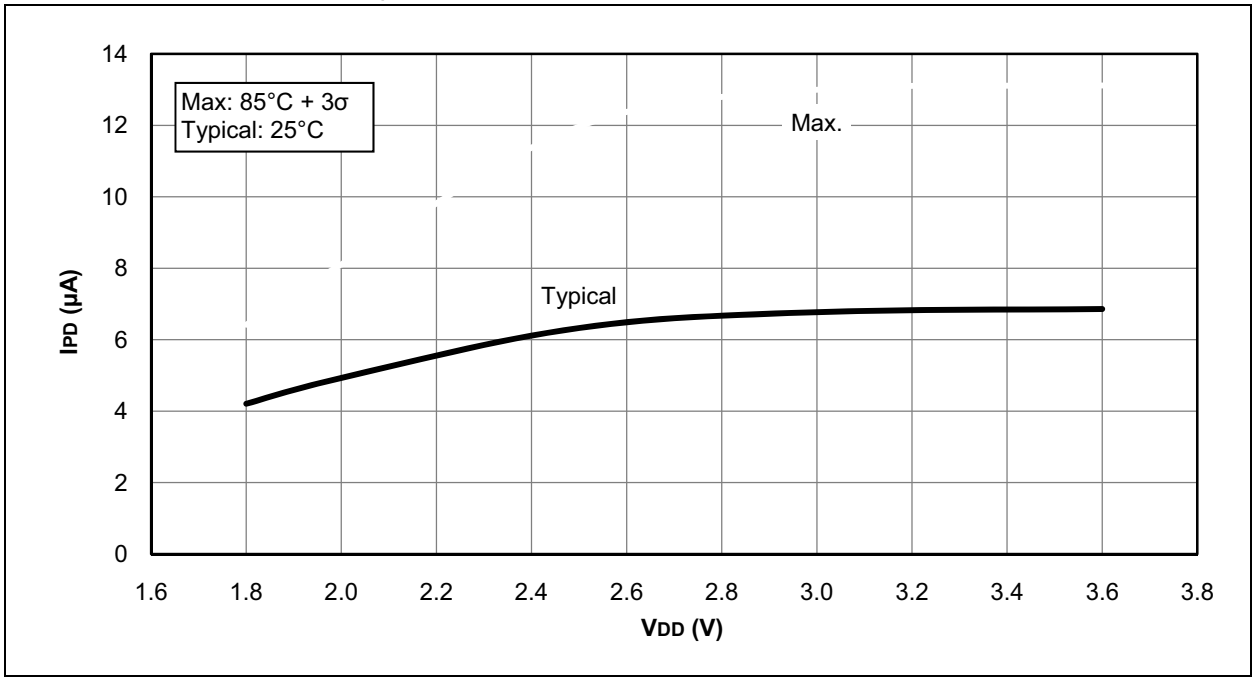


FIGURE 31-44: IPD, CAPACITIVE SENSING (CPS) MODULE, MEDIUM-CURRENT RANGE, CPSRM = 0, PIC16F1946/47 ONLY

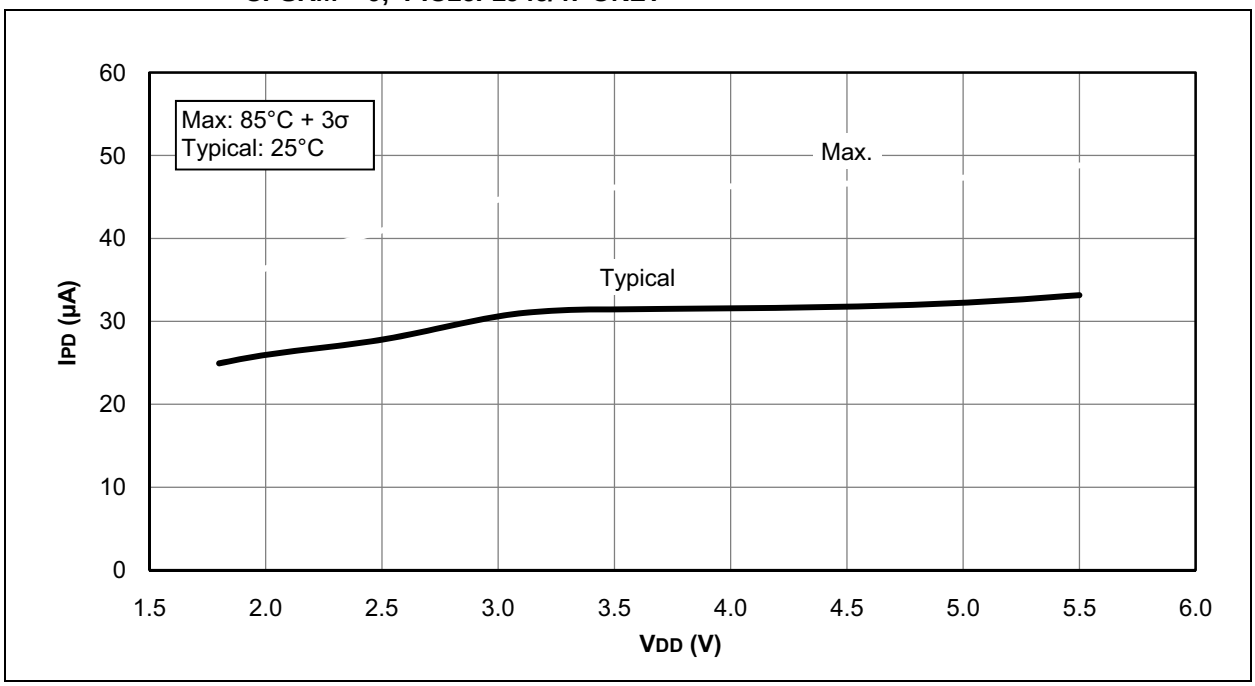


FIGURE 31-63: COMPARATOR RESPONSE TIME, HIGH-POWER MODE

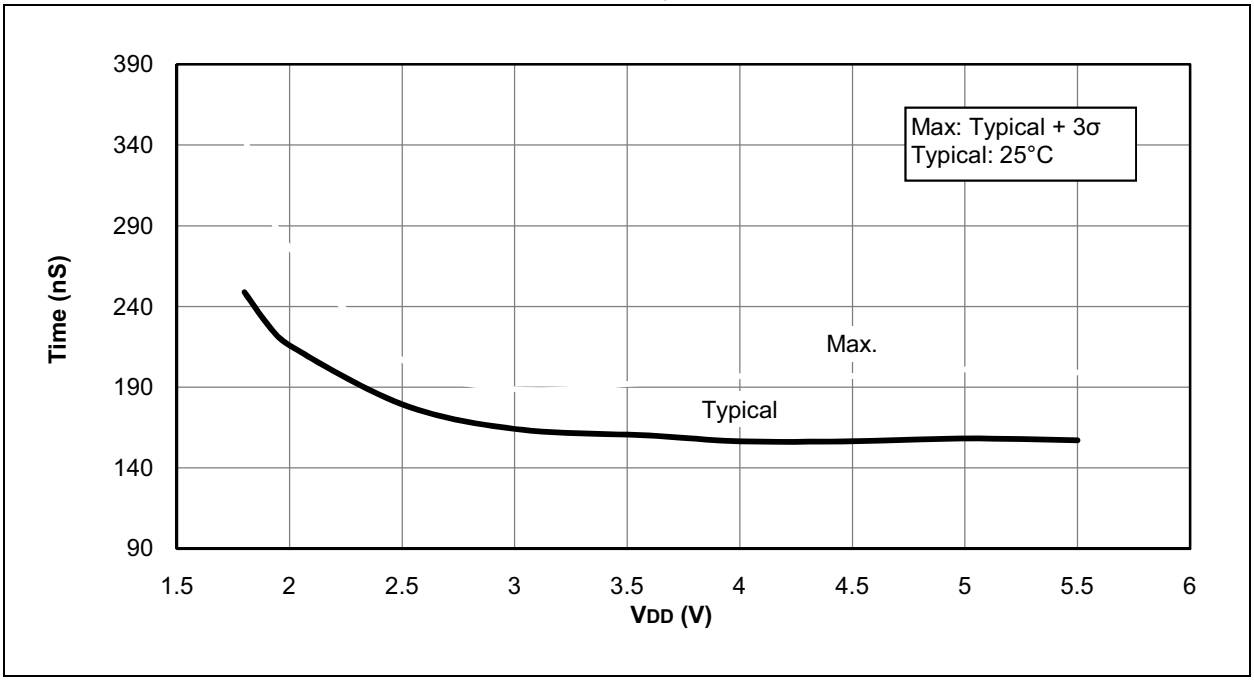


FIGURE 31-64: COMPARATOR RESPONSE TIME OVER TEMPERATURE, HIGH-POWER MODE